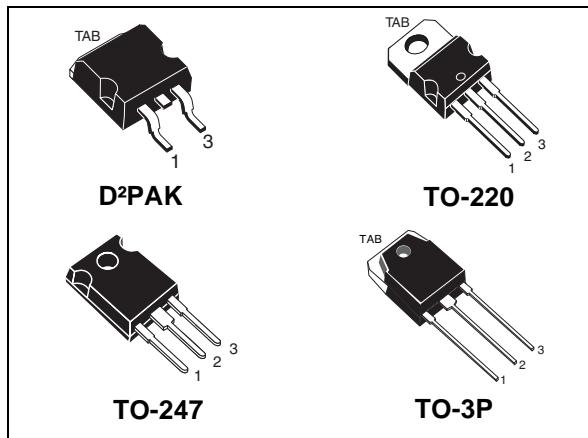


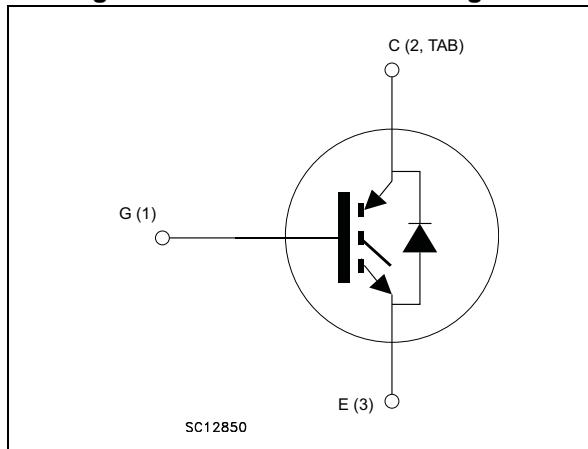
# STGB30V60DF, STGP30V60DF, STGW30V60DF, STGWT30V60DF

Trench gate field-stop IGBT, V series  
600 V, 30 A very high speed

Datasheet - production data



**Figure 1. Internal schematic diagram**



## Features

- Maximum junction temperature:  $T_J = 175 \text{ }^{\circ}\text{C}$
- Tail-less switching off
- $V_{CE(\text{sat})} = 1.85 \text{ V (typ.)} @ I_C = 30 \text{ A}$
- Tight parameters distribution
- Safe paralleling
- Low thermal resistance
- Very fast soft recovery antiparallel diode

## Applications

- Photovoltaic inverters
- Uninterruptible power supply
- Welding
- Power factor correction
- Very high frequency converters

## Description

This device is an IGBT developed using an advanced proprietary trench gate field stop structure. The device is part of the V series of IGBTs, which represent an optimum compromise between conduction and switching losses to maximize the efficiency of very high frequency converters. Furthermore, a positive  $V_{CE(\text{sat})}$  temperature coefficient and very tight parameter distribution result in safer paralleling operation.

**Table 1. Device summary**

Order codes	Marking	Package	Packaging
STGB30V60DF	GB30V60DF	D2PAK	Tape and reel
STGP30V60DF	GP30V60DF	TO-220	Tube
STGW30V60DF	GW30V60DF	TO-247	Tube
STGWT30V60DF	GWT30V60DF	TO-3P	Tube

# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0$ )	600	V
$I_C$	Continuous collector current at $T_C = 25^\circ\text{C}$	60	A
$I_C$	Continuous collector current at $T_C = 100^\circ\text{C}$	30	A
$I_{CP}^{(1)}$	Pulsed collector current	120	A
$V_{GE}$	Gate-emitter voltage	$\pm 20$	V
$I_F$	Continuous forward current at $T_C = 25^\circ\text{C}$	60	A
$I_F$	Continuous forward current at $T_C = 100^\circ\text{C}$	30	A
$I_{FP}^{(1)}$	Pulsed forward current	120	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$	258	W
$T_{STG}$	Storage temperature range	- 55 to 150	$^\circ\text{C}$
$T_J$	Operating junction temperature	- 55 to 175	$^\circ\text{C}$

1. Pulse width limited by maximum junction temperature.

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance junction-case IGBT	0.58	$^\circ\text{C}/\text{W}$
$R_{thJC}$	Thermal resistance junction-case diode	2.08	$^\circ\text{C}/\text{W}$
$R_{thJA}$	Thermal resistance junction-ambient	50	$^\circ\text{C}/\text{W}$

## 2 Electrical characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified.

Table 4. Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage ( $V_{GE} = 0$ )	$I_C = 2 \text{ mA}$	600			V
$V_{CE(\text{sat})}$	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}$		1.85	2.3	V
		$V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}$ $T_J = 125^\circ\text{C}$		2.15		
		$V_{GE} = 15 \text{ V}, I_C = 30 \text{ A}$ $T_J = 175^\circ\text{C}$		2.35		
$V_F$	Forward on-voltage	$I_F = 30 \text{ A}$		2	2.6	V
		$I_F = 30 \text{ A}, T_J = 125^\circ\text{C}$		1.7		V
		$I_F = 30 \text{ A}, T_J = 175^\circ\text{C}$		1.6		V
$V_{GE(\text{th})}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1 \text{ mA}$	5	6	7	V
$I_{CES}$	Collector cut-off current ( $V_{GE} = 0$ )	$V_{CE} = 600 \text{ V}$			25	$\mu\text{A}$
$I_{GES}$	Gate-emitter leakage current ( $V_{CE} = 0$ )	$V_{GE} = \pm 20 \text{ V}$			250	nA

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input capacitance	$V_{CE} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GE} = 0$	-	3750	-	pF
$C_{oes}$	Output capacitance		-	120	-	pF
$C_{res}$	Reverse transfer capacitance		-	77	-	pF
$Q_g$	Total gate charge	$V_{CC} = 480 \text{ V}, I_C = 30 \text{ A}, V_{GE} = 15 \text{ V}$ , see <a href="#">Figure 29</a>	-	163	-	nC
$Q_{ge}$	Gate-emitter charge		-	28	-	nC
$Q_{gc}$	Gate-collector charge		-	72	-	nC

**Table 6. IGBT switching characteristics (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 30 \text{ A}, R_G = 10 \Omega, V_{GE} = 15 \text{ V}$ , see <a href="#">Figure 28</a>	-	45	-	ns
$t_r$	Current rise time		-	16	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1500	-	A/ $\mu\text{s}$
$t_{d(off)}$	Turn-off delay time		-	189	-	ns
$t_f$	Current fall time		-	19	-	ns
$E_{on}^{(1)}$	Turn-on switching losses		-	383	-	$\mu\text{J}$
$E_{off}^{(2)}$	Turn-off switching losses		-	233	-	$\mu\text{J}$
$E_{ts}$	Total switching losses		-	616	-	$\mu\text{J}$
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 30 \text{ A}, R_G = 10 \Omega, V_{GE} = 15 \text{ V}, T_J = 175 \text{ }^\circ\text{C}$ , see <a href="#">Figure 28</a>	-	42	-	ns
$t_r$	Current rise time		-	17	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1337	-	A/ $\mu\text{s}$
$t_{d(off)}$	Turn-off delay time		-	193	-	ns
$t_f$	Current fall time		-	32	-	ns
$E_{on}^{(1)}$	Turn-on switching losses		-	794	-	$\mu\text{J}$
$E_{off}^{(2)}$	Turn-off switching losses		-	378	-	$\mu\text{J}$
$E_{ts}$	Total switching losses		-	1172	-	$\mu\text{J}$

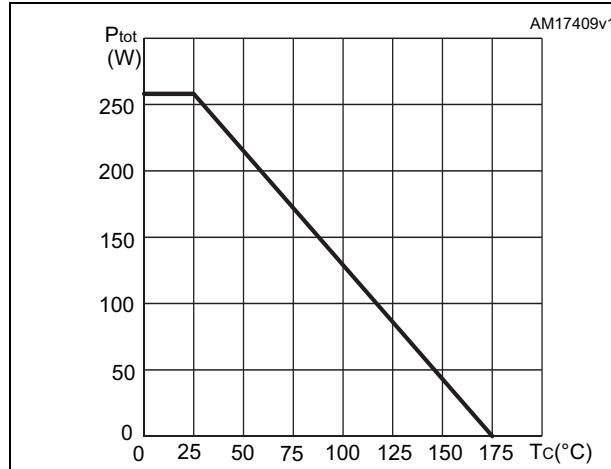
1. Energy losses include reverse recovery of the diode.
2. Turn-off losses include also the tail of the collector current.

**Table 7. Diode switching characteristics (inductive load)**

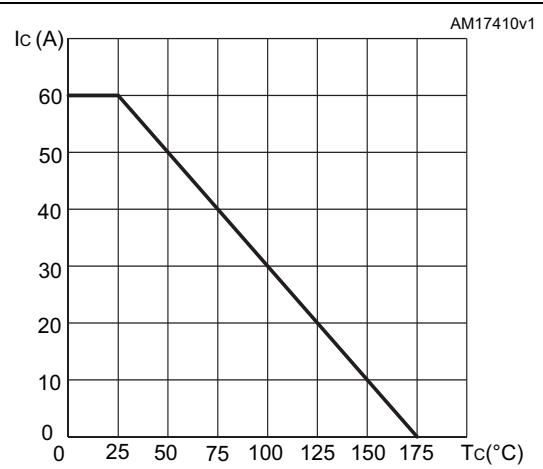
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$I_F = 30 \text{ A}, V_R = 400 \text{ V}, di/dt=1000 \text{ A}/\mu\text{s}, V_{GE} = 15 \text{ V}$ , (see <a href="#">Figure 28</a> )	-	53	-	ns
$Q_{rr}$	Reverse recovery charge		-	384	-	nC
$I_{rrm}$	Reverse recovery current		-	14.5	-	A
$dI_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$		-	788	-	A/ $\mu\text{s}$
$E_{rr}$	Reverse recovery energy		-	104	-	$\mu\text{J}$
$t_{rr}$	Reverse recovery time	$I_F = 30 \text{ A}, V_R = 400 \text{ V}, di/dt=1000 \text{ A}/\mu\text{s}, V_{GE} = 15 \text{ V}, T_J = 175 \text{ }^\circ\text{C}$ , (see <a href="#">Figure 28</a> )	-	104	-	ns
$Q_{rr}$	Reverse recovery charge		-	1352	-	nC
$I_{rrm}$	Reverse recovery current		-	26	-	A
$dI_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$		-	310	-	A/ $\mu\text{s}$
$E_{rr}$	Reverse recovery energy		-	407	-	$\mu\text{J}$

## 2.1 Electrical characteristics (curves)

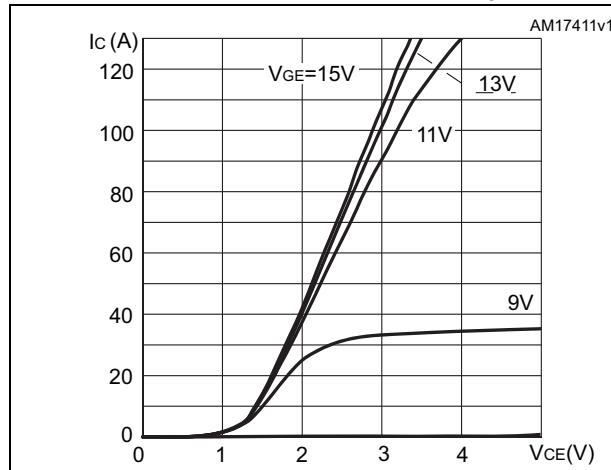
**Figure 2. Power dissipation vs. case temperature**



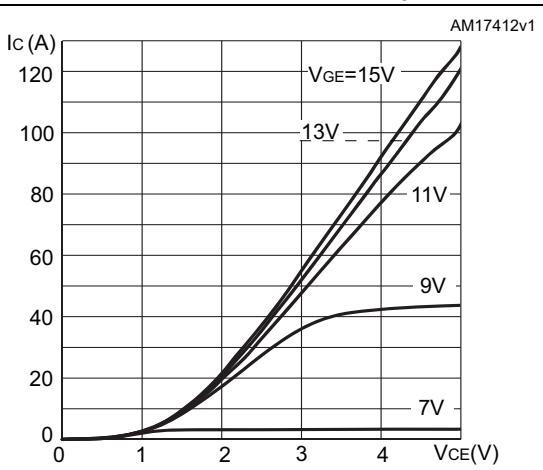
**Figure 3. Collector current vs. case temperature**



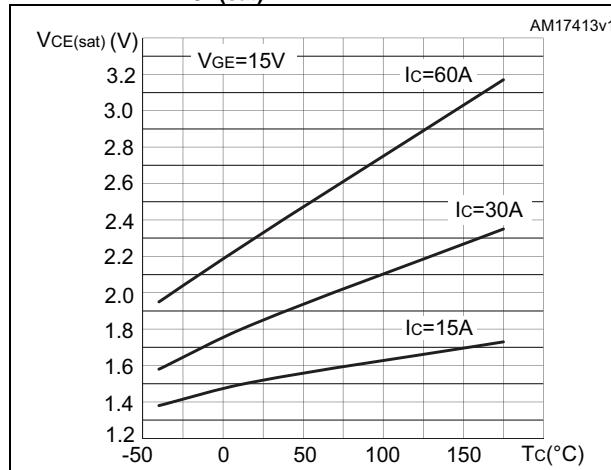
**Figure 4. Output characteristics ( $T_j=25^\circ\text{C}$ )**



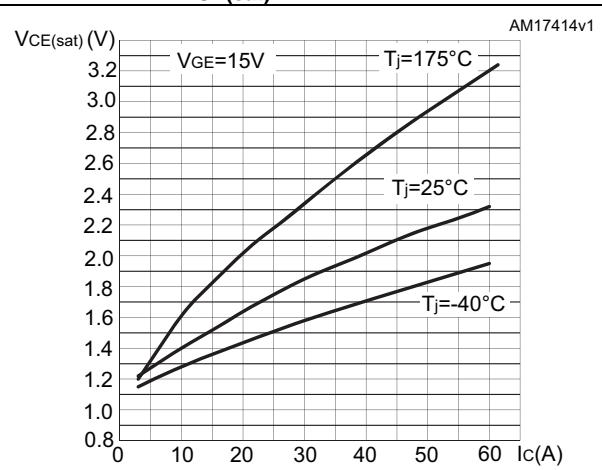
**Figure 5. Output characteristics ( $T_j=175^\circ\text{C}$ )**

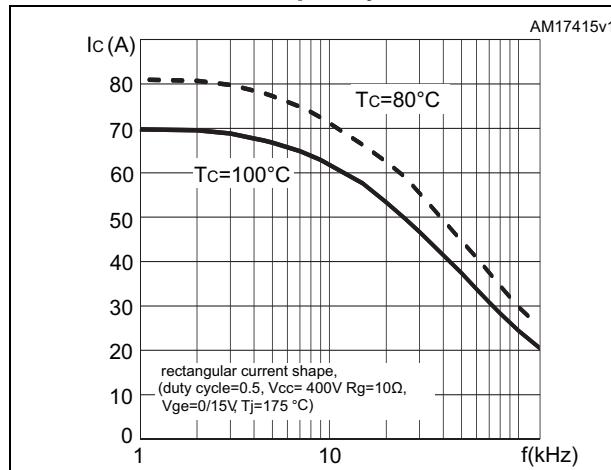
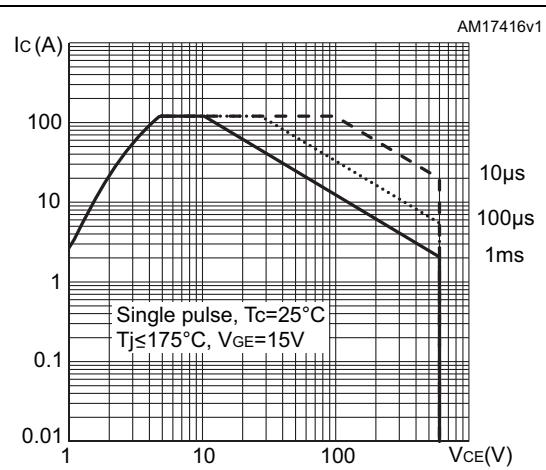
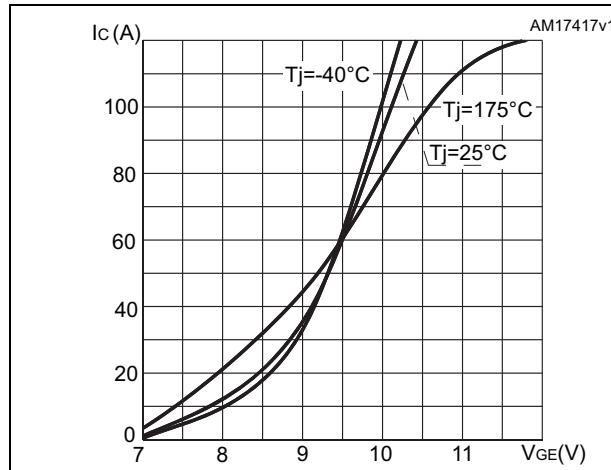
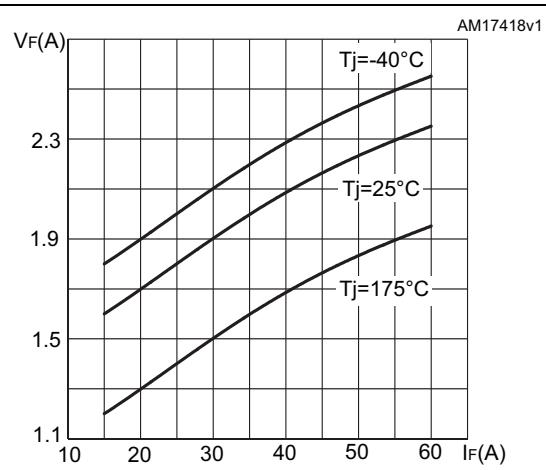
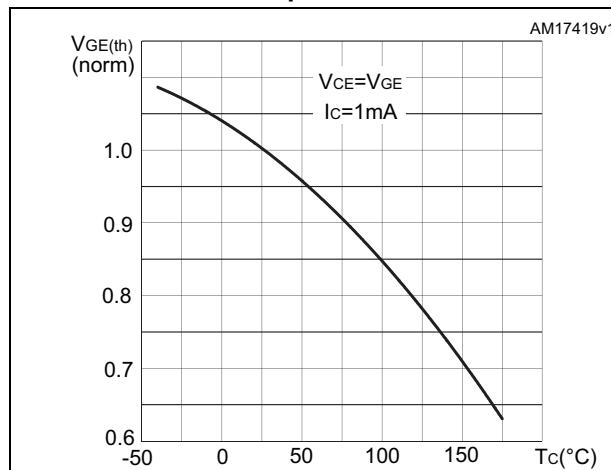
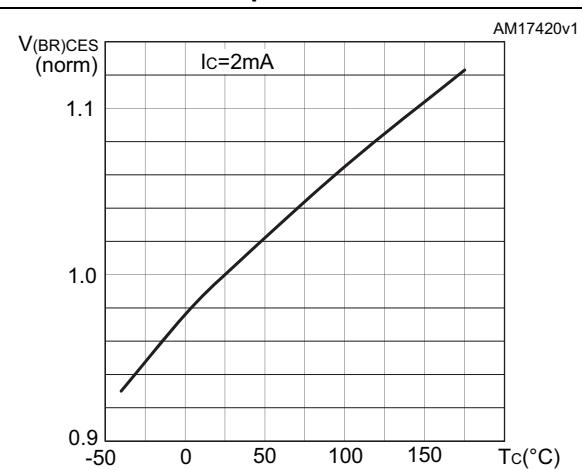


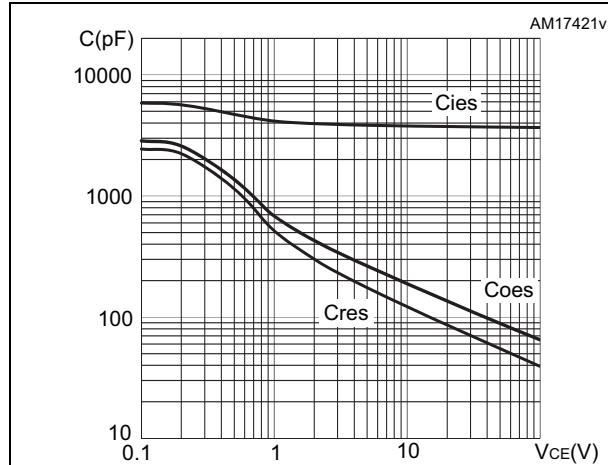
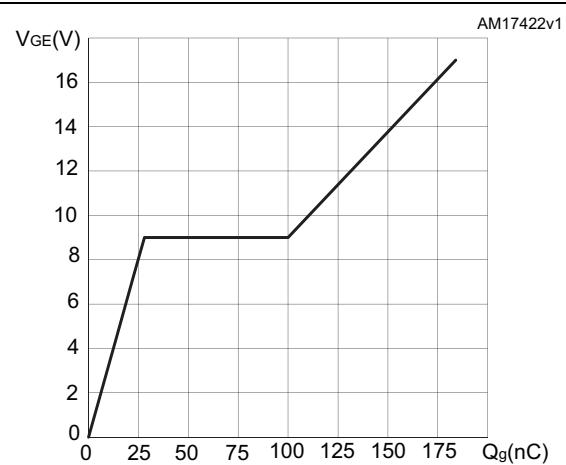
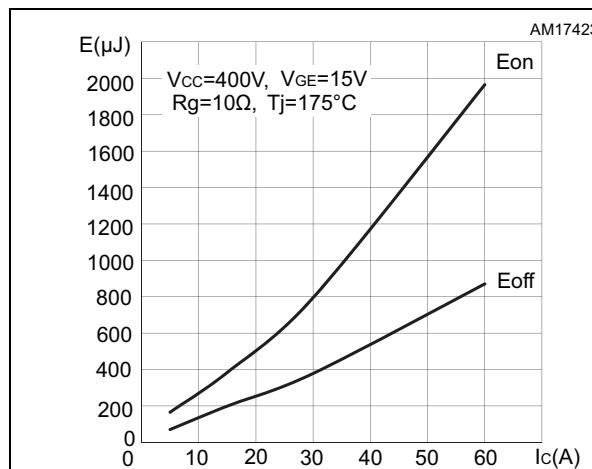
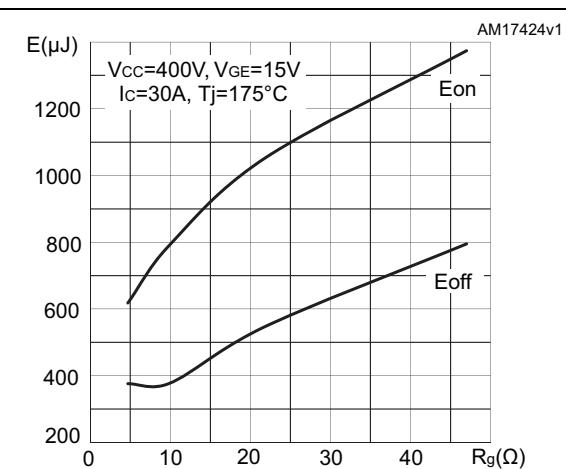
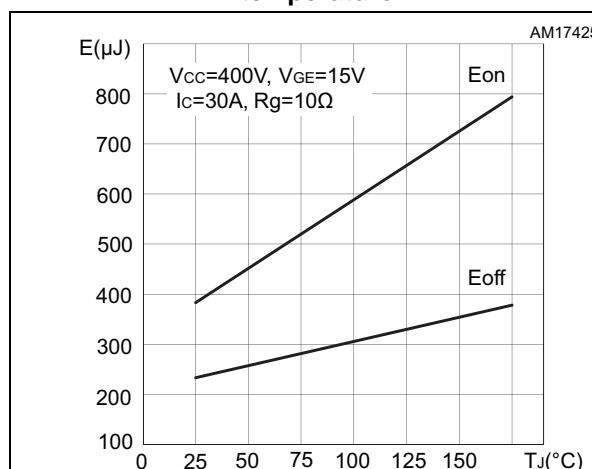
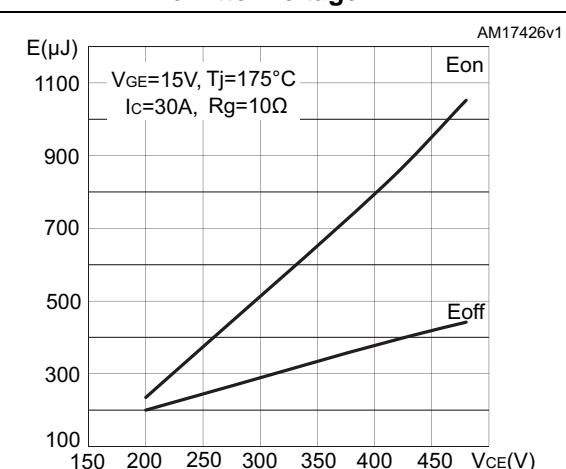
**Figure 6.  $V_{CE(\text{sat})}$  vs. junction temperature**



**Figure 7.  $V_{CE(\text{sat})}$  vs. collector current**



**Figure 8. Collector current vs. switching frequency****Figure 9. Forward bias safe operating area****Figure 10. Transfer characteristics****Figure 11. Diode  $V_F$  vs. forward current****Figure 12. Normalized  $V_{GE(th)}$  vs junction temperature****Figure 13. Normalized  $V_{(BR)CES}$  vs. junction temperature**

**Figure 14. Capacitance variations****Figure 15. Gate charge vs. gate-emitter voltage****Figure 16. Switching losses vs. collector current****Figure 17. Switching losses vs. gate resistance****Figure 18. Switching losses vs. junction temperature****Figure 19. Switching losses vs. collector-emitter voltage**

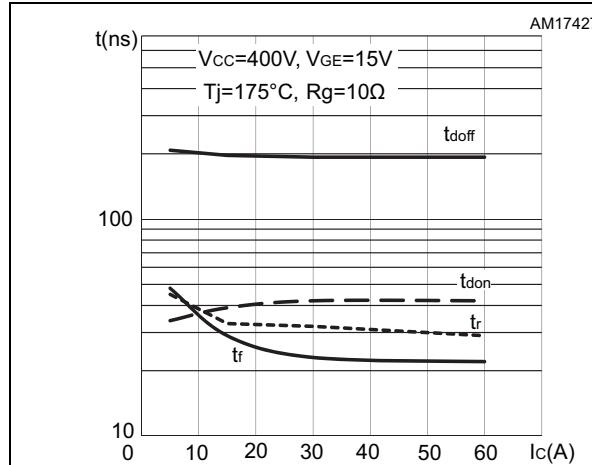
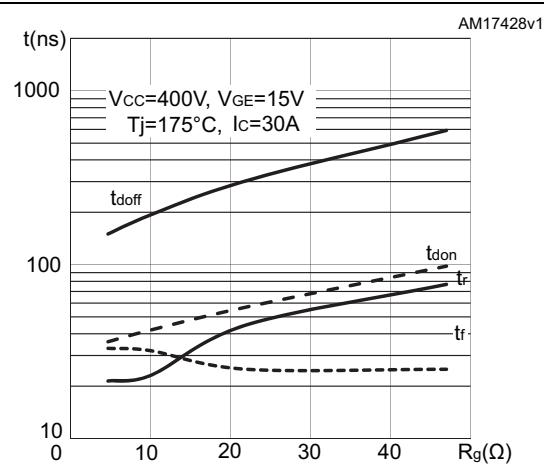
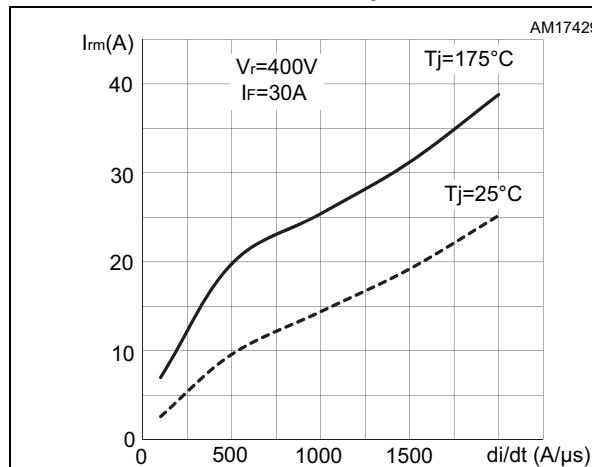
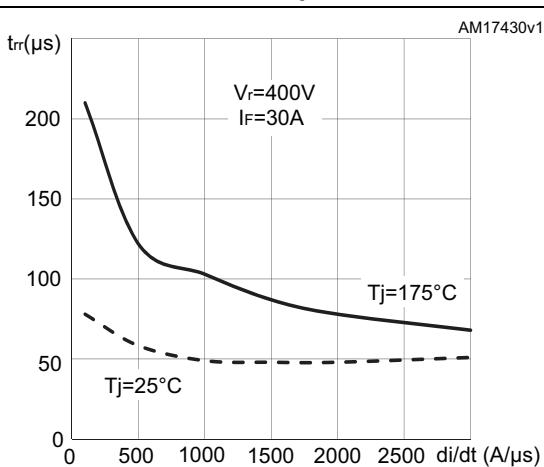
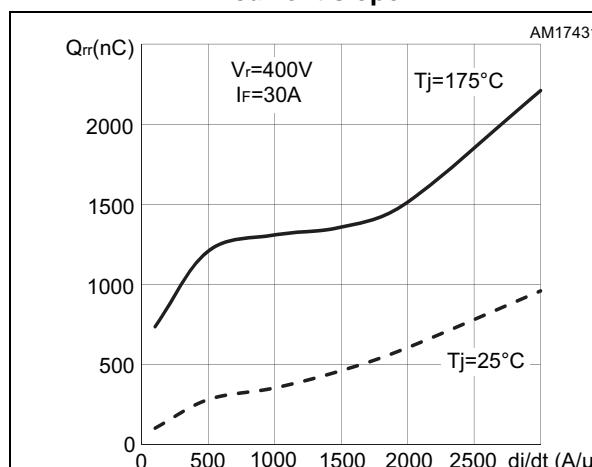
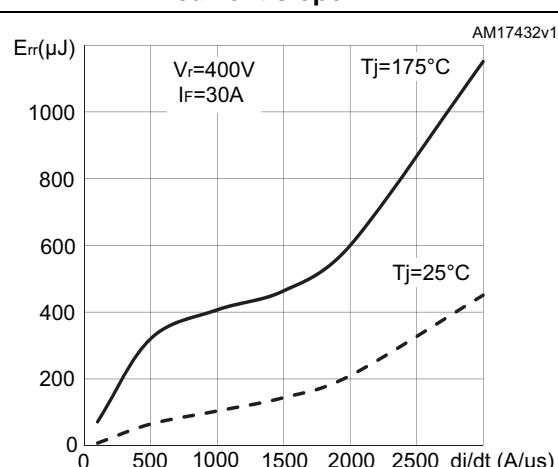
**Figure 20. Switching times vs. collector current****Figure 21. Switching times vs. gate resistance****Figure 22. Reverse recovery current vs. diode current slope****Figure 23. Reverse recovery time vs. diode current slope****Figure 24. Reverse recovery charge vs. diode current slope****Figure 25. Reverse recovery energy vs. diode current slope**

Figure 26. Thermal data for IGBT

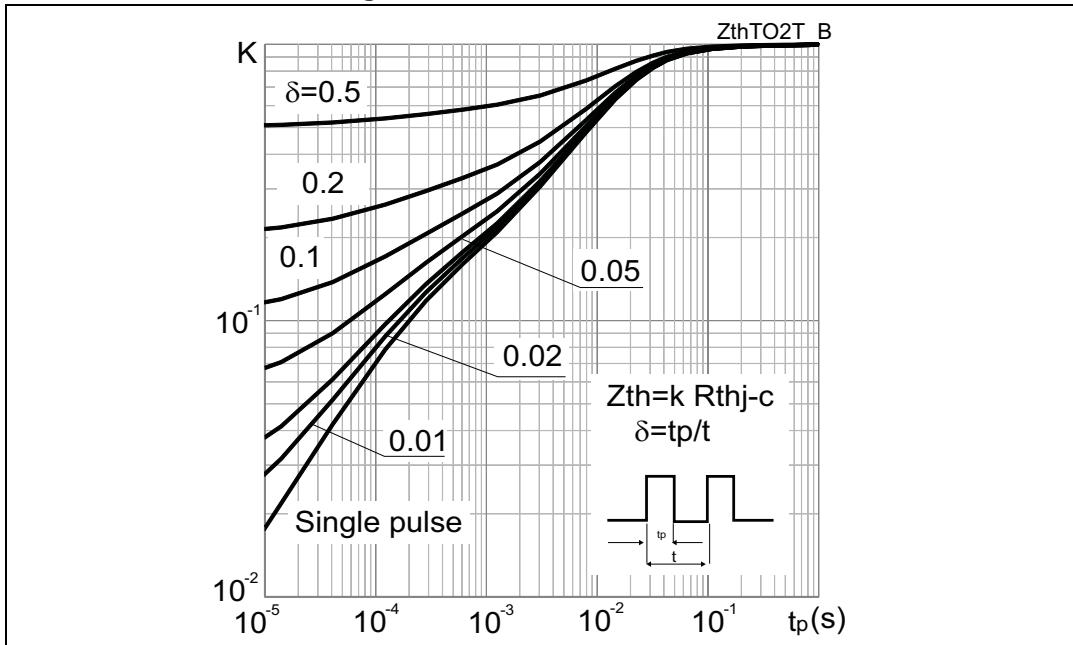
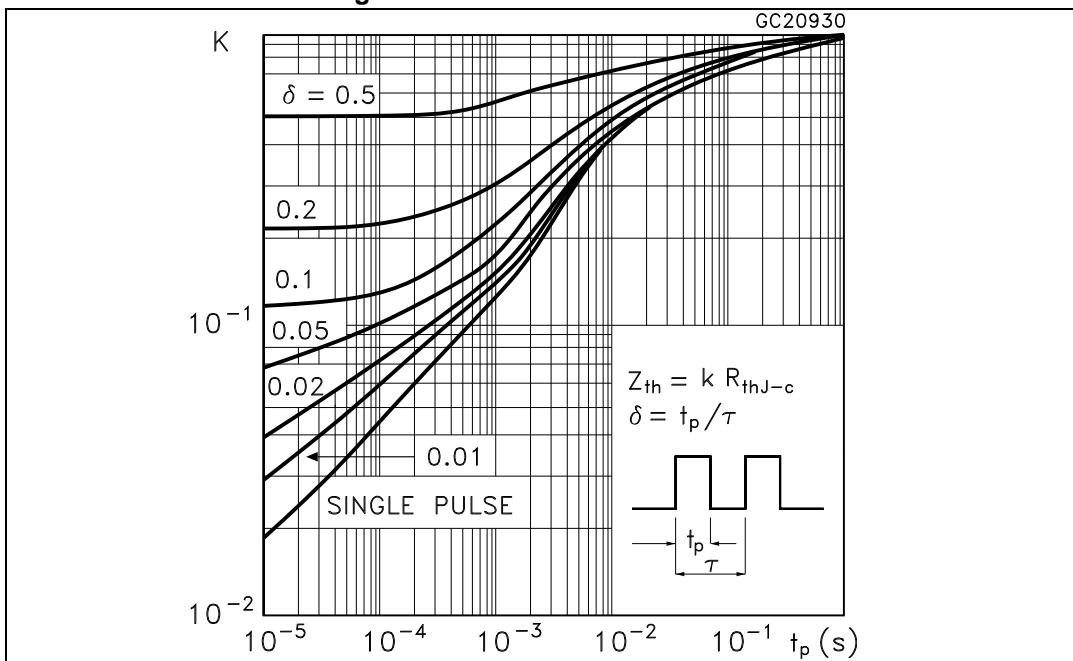
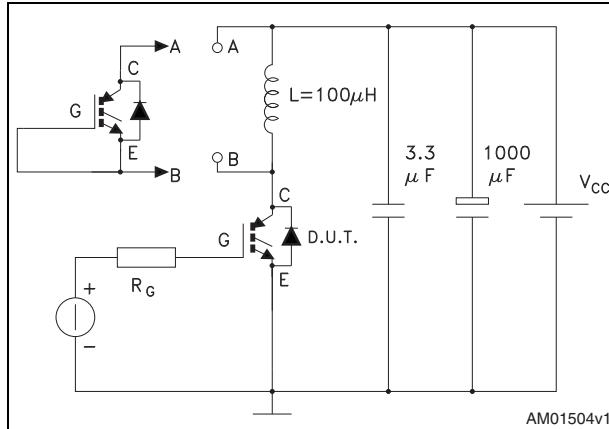


Figure 27. Thermal data for diode

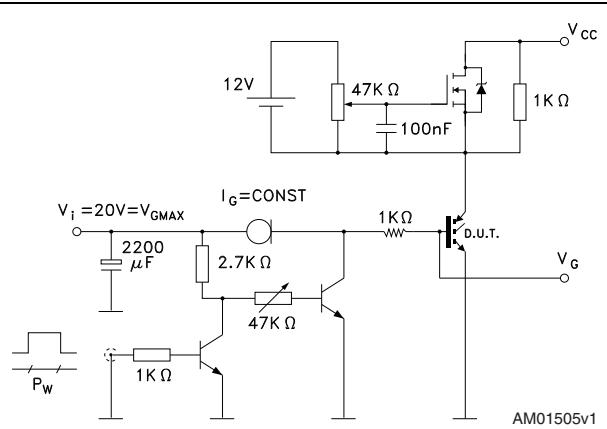


### 3 Test circuits

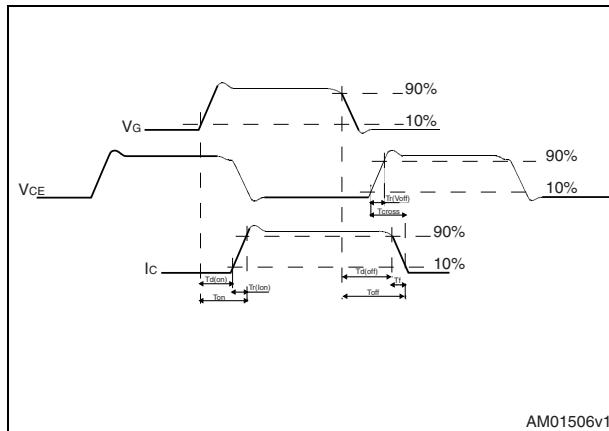
**Figure 28. Test circuit for inductive load switching**



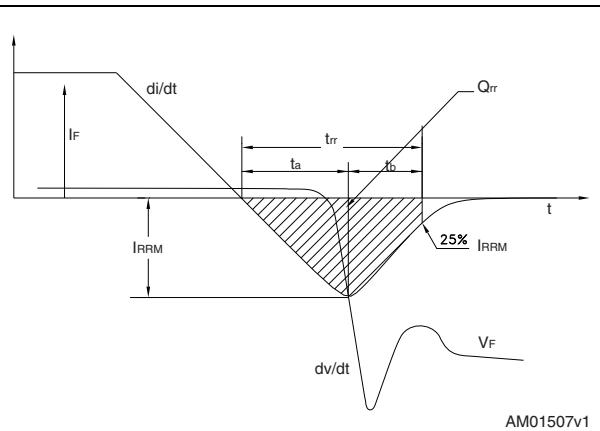
**Figure 29. Gate charge test circuit**



**Figure 30. Switching waveform**



**Figure 31. Diode recovery time waveform**

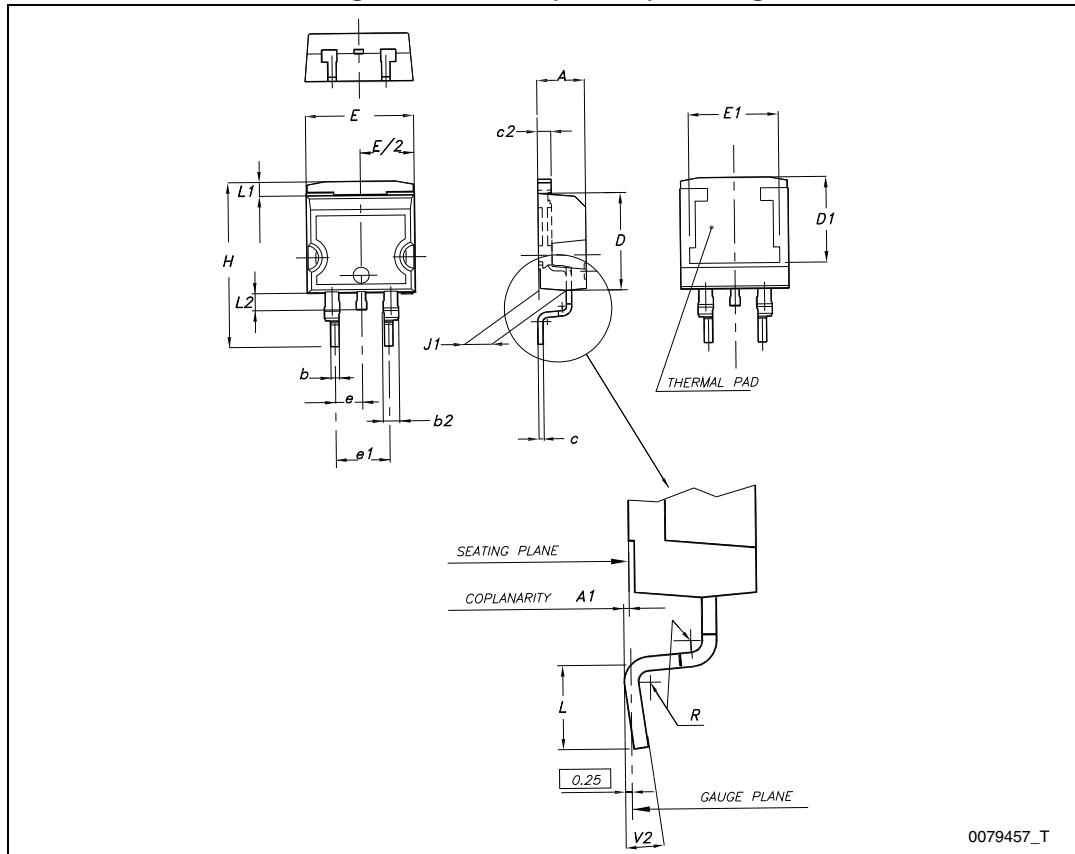
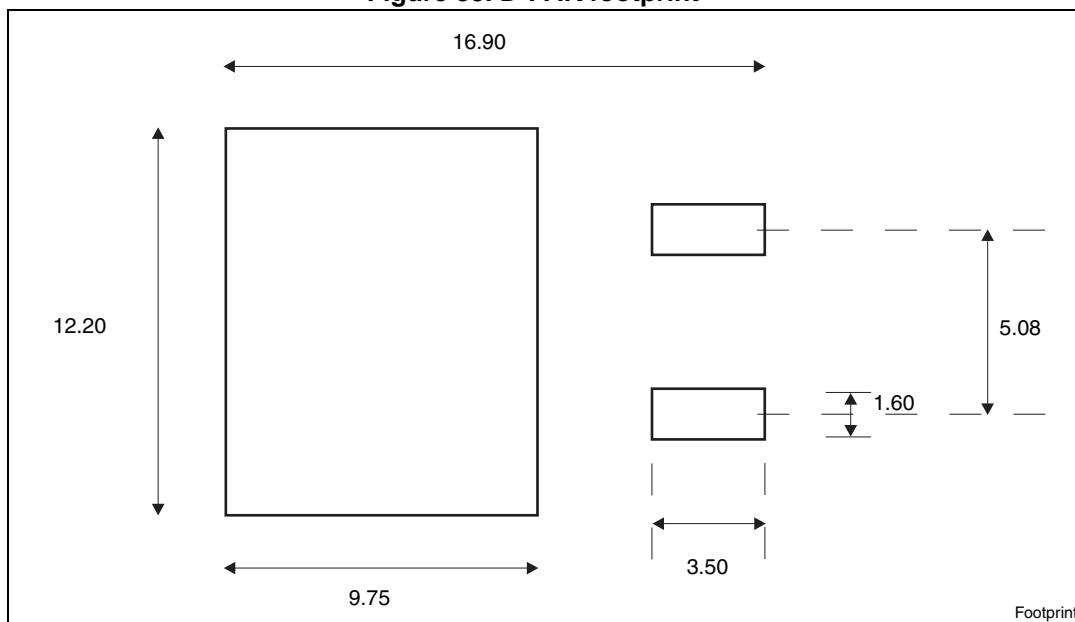


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
ECOPACK is an ST trademark.

**Table 8. D<sup>2</sup>PAK (TO-263) mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50		
E	10		10.40
E1	8.50		
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

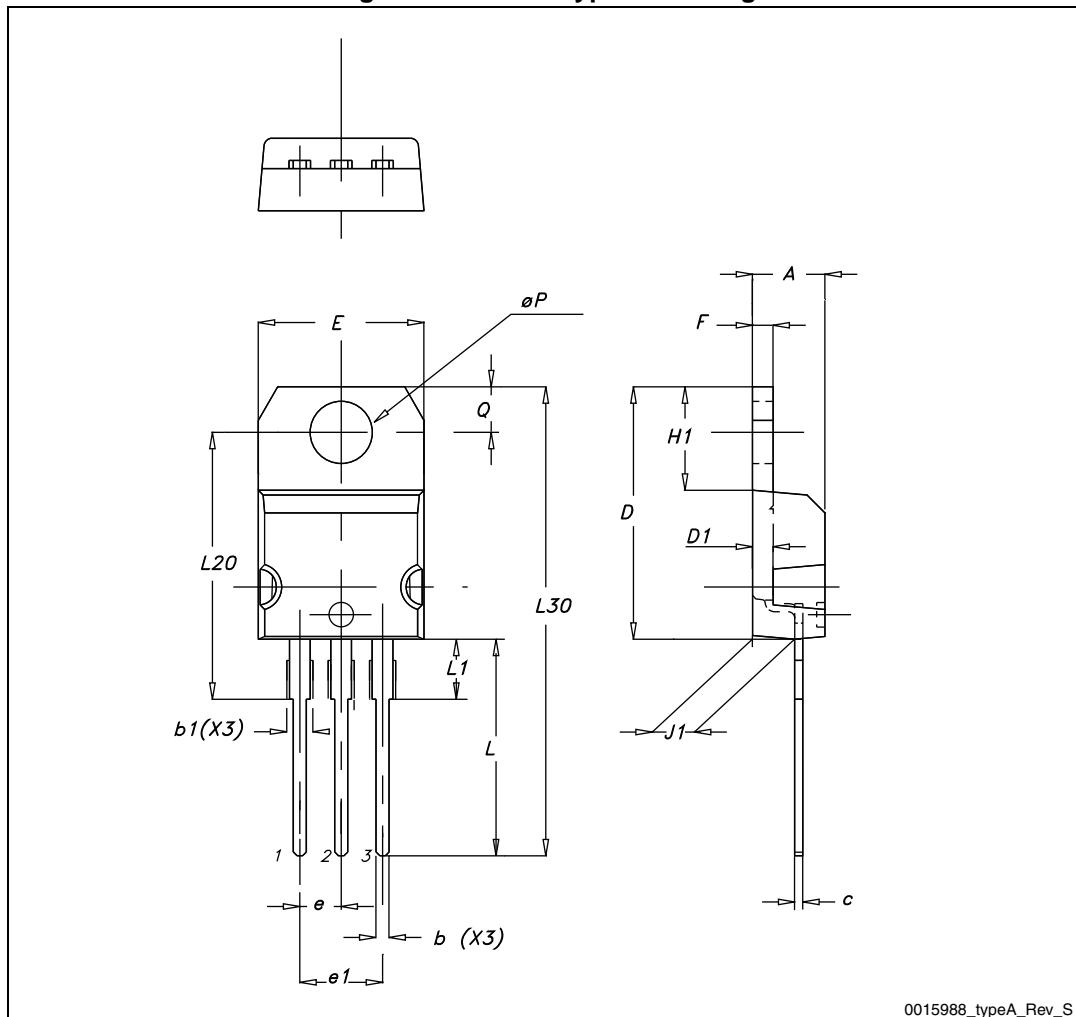
Figure 32. D<sup>2</sup>PAK (TO-263) drawingFigure 33. D<sup>2</sup>PAK footprint<sup>(a)</sup>

a. All dimensions are in millimeters

**Table 9. TO-220 type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

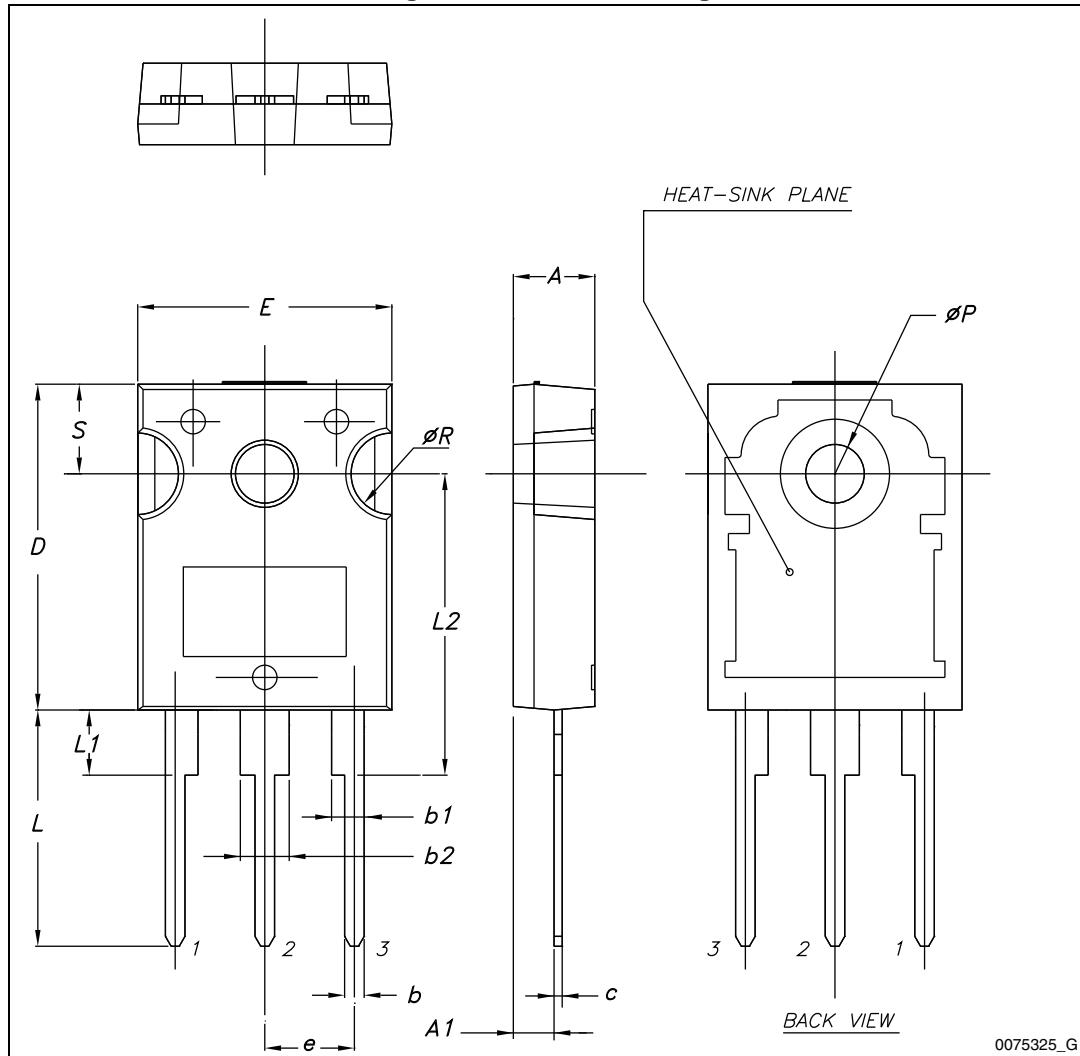
Figure 34. TO-220 type A drawing



**Table 10. TO-247 mechanical data**

Dim.	mm.		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

Figure 35. TO-247 drawing

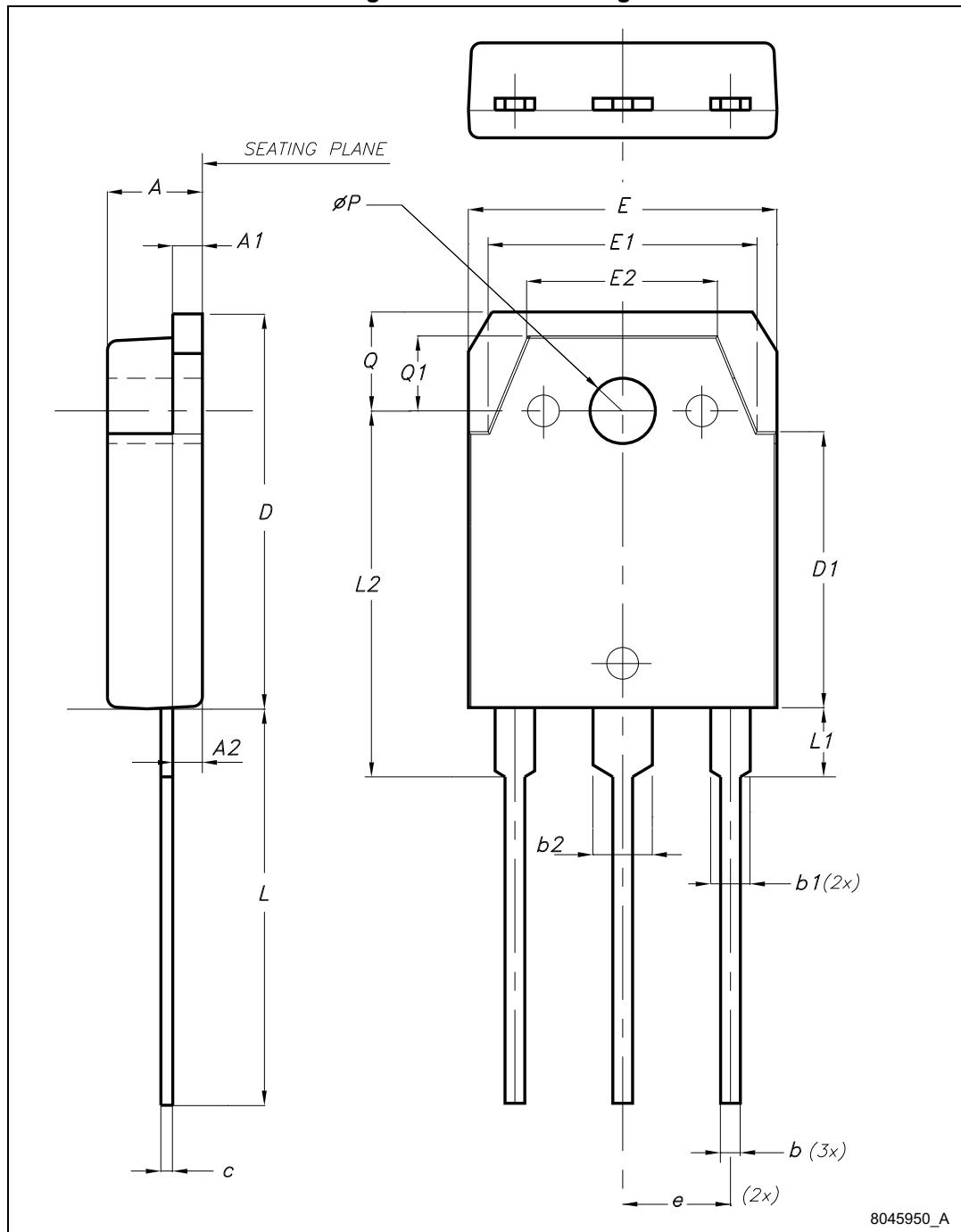


0075325\_G

**Table 11. TO-3P mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.60		5
A1	1.45	1.50	1.65
A2	1.20	1.40	1.60
b	0.80	1	1.20
b1	1.80		2.20
b2	2.80		3.20
c	0.55	0.60	0.75
D	19.70	19.90	20.10
D1		13.90	
E	15.40		15.80
E1		13.60	
E2		9.60	
e	5.15	5.45	5.75
L	19.50	20	20.50
L1		3.50	
L2	18.20	18.40	18.60
øP	3.10		3.30
Q		5	
Q1		3.80	

Figure 36. TO-3P drawing

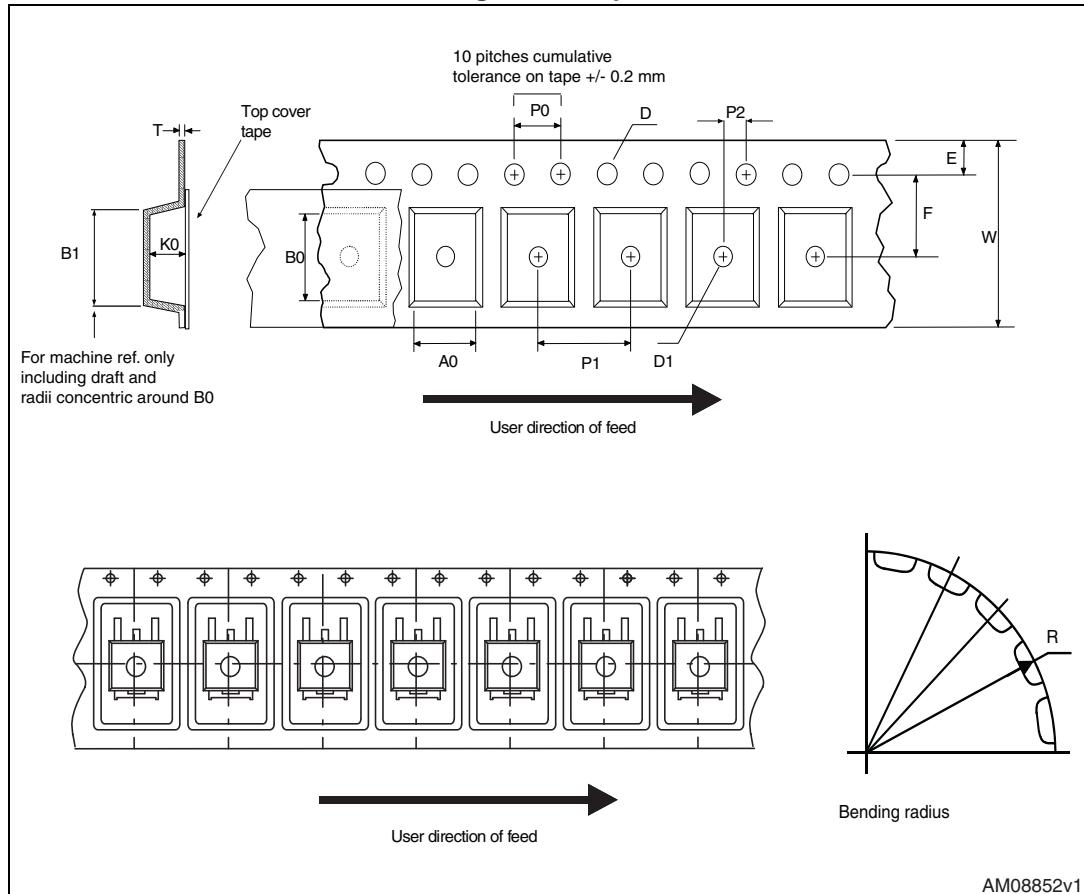


## 5 Packaging mechanical data

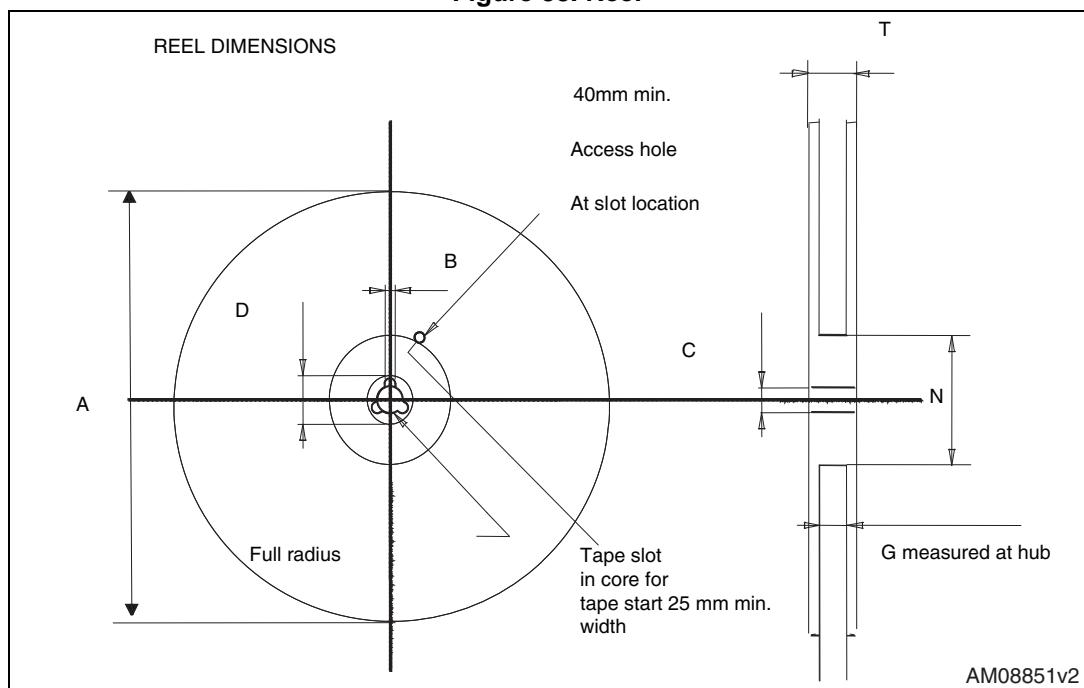
**Table 12. D<sup>2</sup>PAK (TO-263) tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base qty	1000
P2	1.9	2.1		Bulk qty	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

**Figure 37. Tape**



**Figure 38.** Reel



## 6 Revision history

Table 13. Document revision history

Date	Revision	Changes
14-Mar-2013	1	Initial release.
03-May-2013	2	Added: <a href="#">Section 2.1: Electrical characteristics (curves)</a>
04-Jun-2013	3	Added minimum and maximum values for $V_{GE(th)}$ in <a href="#">Table 4: Static characteristics</a> .
08-Oct-2013	4	Updated title, features and description in cover page.

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